

ABSTRACT

Disclosed is a flip chip bonding device and a bonding method. The bonding device comprises: a supply unit (10) configured to separate a flip-chip (200) from a carrier (100) and to provide the flip-chip (200), and comprising a flipping device (11); a transfer unit (20) configured to receive the flip-chip (200) from the flipping device (11); a position adjustment unit (30) configured to adjust the position of the flip-chips (200) on the transfer unit (20); a bonding unit (40) configured to bond the flip-chips (200) on the transfer unit (20) to a substrate (400); a transport unit (50) configured to transport the transfer unit (20); and a control unit (60) configured to control the movement of each of the units. Since the transfer unit (20) can handle multiple flip-chips (200), the present invention can complete bonding of multiple flip-chips (200) at one time, thereby saving bonding time and increasing bonding efficiency. In addition, the transfer unit (20) passes through the position adjustment unit (30) during transport, and the position adjustment unit (30) adjusts the position of the flip-chips (200) on the transfer unit (20) so as to ensure accurate positioning of the flip-chips (200) during the subsequent bonding process, achieving highly accurate bonding.